

US-PAT-NO: 4365041

DOCUMENT-IDENTIFIER: US 4365041 A

TITLE: Resin composition comprising water-soluble polyamide and vinyl alcohol-based polymer

----- KWIC -----

Brief Summary Text - BSTX (11):

As is well known in the art, vinyl alcohol-based polymers have also been used heretofore as adhesives. Since the vinyl alcohol-based polymer is not generally easily melted by heat owing to the strong hydrogen bond formed between hydroxyl groups which are contained in the vinyl alcohol-based polymer, it is usually dissolved in **water as a solvent to provide an adhesive**. The thus-obtained adhesive, however, has the disadvantage that a drying step is required after the coating of the adhesive. This produces problems in operation and imposes limitations on the usefulness.

Brief Summary Text - BSTX (14):

Furthermore, Japanese Patent Application (OPI) No. 96831/1976 (The term "OPI" as used herein refers to a "published unexamined Japanese patent application") discloses a composition comprising polyvinyl alcohol and polyethylene glycol, and Japanese Patent Application (OPI) No. 96832/1976 describes that a **composition comprising polyvinyl alcohol, an ethylene-vinyl acetate** copolymer, and a plasticizer is useful as a water-soluble hot melt type of adhesive. In both compositions, however, polyvinyl alcohol having a low average degree of polymerization and a low degree of saponification, i.e., having many residual acetic acid groups is inevitably used in order to provide both water-solubility and hot melt properties thereto. For example, in Japanese Patent Application (OPI) Nos. 96831/1976 and 96832/1976, polyvinyl alcohol having an average degree of polymerization of 50 to 300 and containing 15 to 70 mol % of residual acetic acid group is used.